杰力科技股份有限公司
Excelliance MOS Corporation

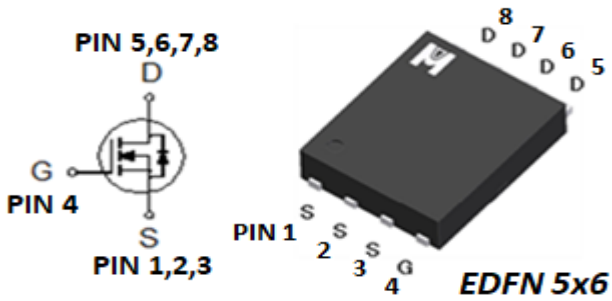
EMB12N10H

Single N-Channel Logic Level Enhancement Mode Field Effect Transistor

▪Product Summary:

	N-CH
BVDSS	100V
$R_{DSON\ (MAX.)}$@V_{GS}=10V	12.0mΩ
$R_{DSON\ (MAX.)}$@V_{GS}=4.5V	15.0mΩ
I_D @T_C=25°C	90.0A
I_D @T_A=25°C	11.0A

▪ Pin Description:



Single N Channel MOSFET
UIS, Rg 100% Tested
Pb-Free Lead Plating & Halogen Free

▪ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C = 25 °C	I_D	90	A
	T_C = 100 °C		57	
Continuous Drain Current	T_A = 25 °C	I_D	11	
	T_A = 70 °C		8	
Pulsed Drain Current[1]		I_{DM}	152	
Avalanche Current		I_{AS}	22	
Avalanche Energy	L = 0.1mH	EAS	24.2	mJ
Repetitive Avalanche Energy[2]	L = 0.05mH	EAR	12.1	
Power Dissipation	T_C = 25 °C	P_D	166.7	W
	T_C = 100 °C		66.7	
Power Dissipation	T_A = 25 °C	P_D	2.5	W
	T_A = 70 °C		1.6	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

▪ 100% UIS testing in condition of VD=50V, L=0.1mH, VG=10V, IL=13.5A, Rated VDS=100V N-CH

▪THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		0.75	°C/W
Junction-to-Ambient[3]	$R_{\theta JA}$		50	

[1]Pulse width limited by maximum junction temperature.
[2]Duty cycle < 1%
[3]50°C / W when mounted on a 1 in^2 pad of 2 oz copper.
[4]Guarantee by Engineering test

▪ **ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage[4]	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250uA	100			V
Gate Threshold Voltage[4]	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250uA	1	1.6	3	V
Gate-Body Leakage[4]	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current[4]	I_{DSS}	V_{DS} = 80V, V_{GS} = 0V			1	uA
		V_{DS} =80V, V_{GS} =0V, T_J = 125 °C			25	uA
On-State Drain Current[1]	$I_{D(ON)}$	V_{DS} =5V, V_{GS} = 10V	90			A
Drain-Source On-State Resistance[1,4]	$R_{DS(ON)}$	V_{GS} = 10V, I_D = 12A		10	12	mΩ
		V_{GS} = 4.5V, I_D = 10A		12	15	mΩ
Forward Transconductance[1]	g_{fs}	V_{DS} = 5V, I_D = 12A		45		S
DYNAMIC						
Input Capacitance[5]	C_{iss}	V_{GS} = 0V, V_{DS} = 50V, f = 1MHz		1595		pF
Output Capacitance[5]	C_{oss}			267		pF
Reverse Transfer Capacitance[5]	C_{rss}			25		pF
Gate Resistance[4,5]	R_g	f = 1MHz		0.8		Ω
Total Gate Charge[1,2,5]	Q_g(V_{GS}=10V)	V_{DS} = 50V, V_{GS} = 10V, I_D = 12A		30.8		nC
	Q_g(V_{GS}=4.5V)			17.4		nC
Gate-Source Charge[1,2,5]	Q_{gs}			3.7		nC
Gate-Drain Charge[1,2,5]	Q_{gd}			9.0		nC
Turn-On Delay Time[1,2,5]	$t_{d(on)}$	V_{DS} = 50V, V_{GS} = 10V, I_D = 5A , Rg = 6Ω		9.4		nS
Rise Time[1,2,5]	t_r			10.7		nS
Turn-Off Delay Time[1,2,5]	$t_{d(off)}$			36.6		nS
Fall Time[1,2,5]	t_f			31.2		nS
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS						
Continuous Current	I_S				90	A
Pulsed Current[3]	I_{SM}				152	A
Forward Voltage[1,4]	V_{SD}	I_F = 10A, V_{GS} = 0V			1.3	V
Reverse Recovery Time[5]	t_{rr}	I_F = 10A, dI_F/dt = 100A / uS		50.0		nS
Reverse Recovery Charge[5]	Q_{rr}			51.4		nC

[1]Pulse test : Pulse Width ≦ 300 usec, Duty Cycle ≦ 2%.

[2]Independent of operating temperature.

[3]Pulse width limited by maximum junction temperature.

[4]Guarantee by FT test Item

[5]Guarantee by Engineering test

▪TYPICAL CHARACTERISTICS

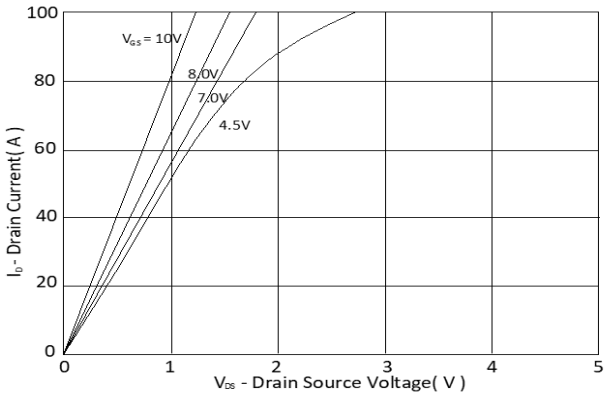


Fig.1 Typical Output Characteristics

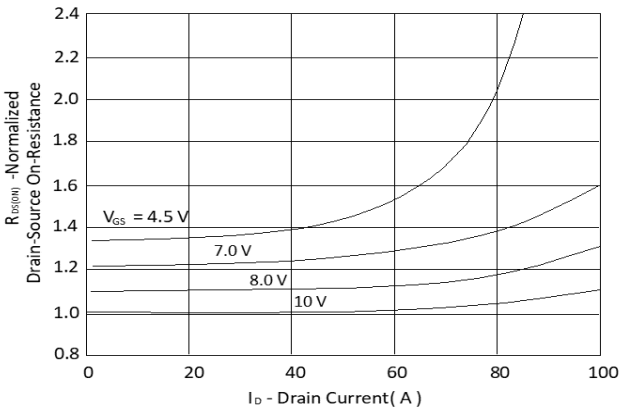


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

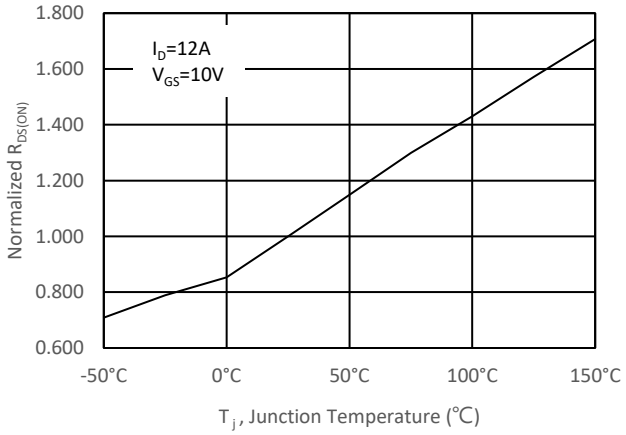


Fig.3 Normalized On-Resistance v.s. Junction Temperature

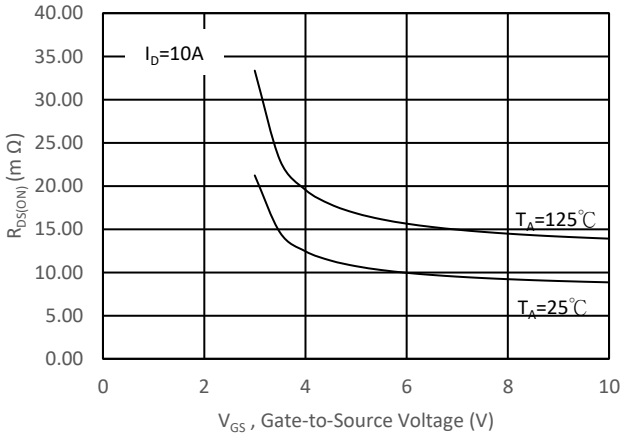


Fig.4 On-Resistance v.s. Gate Voltage

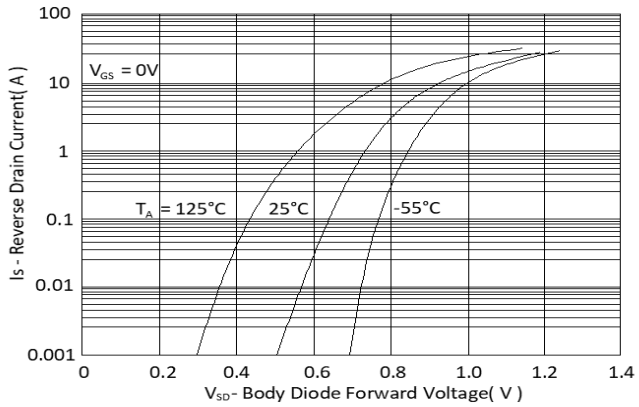


Fig.5 Forward Characteristic of Reverse Diode

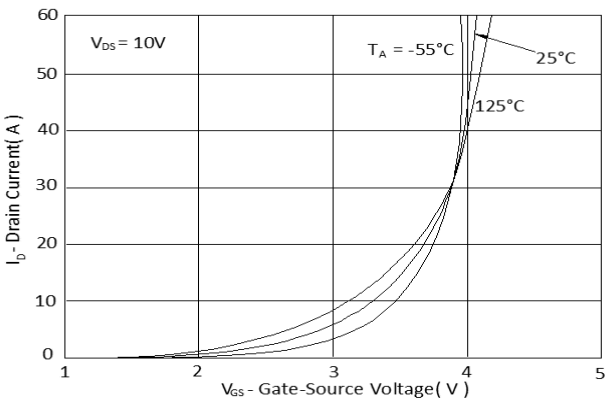


Fig.6 Transfer Characteristics

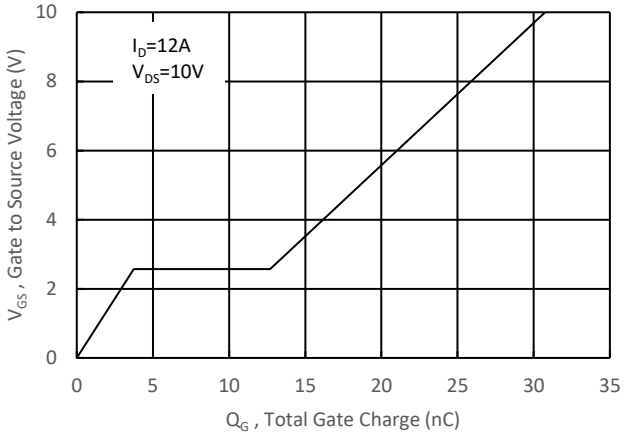


Fig.7 Gate Charge Characteristics

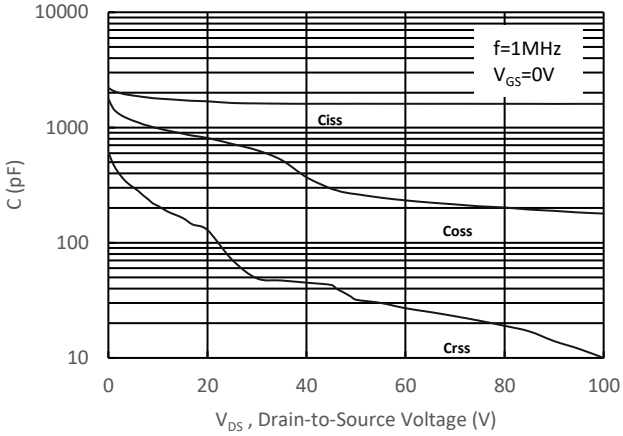


Fig.8 Typical Capacitance Characteristics

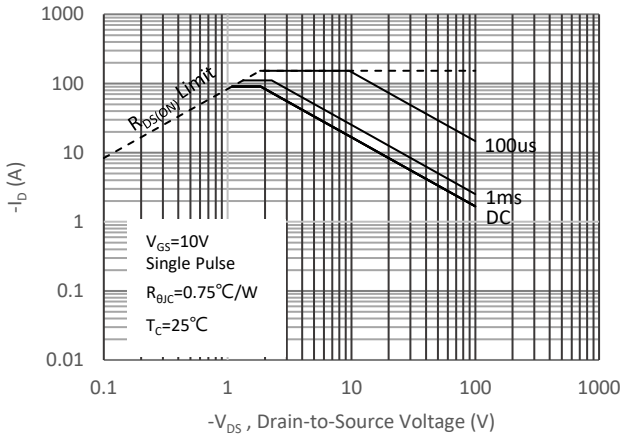


Fig 9. Maximum Safe Operating Area

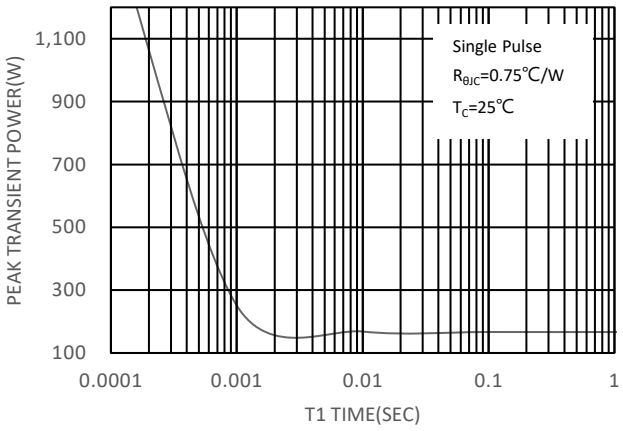


Fig 10. Single Pulse Maximum Power Dissipation

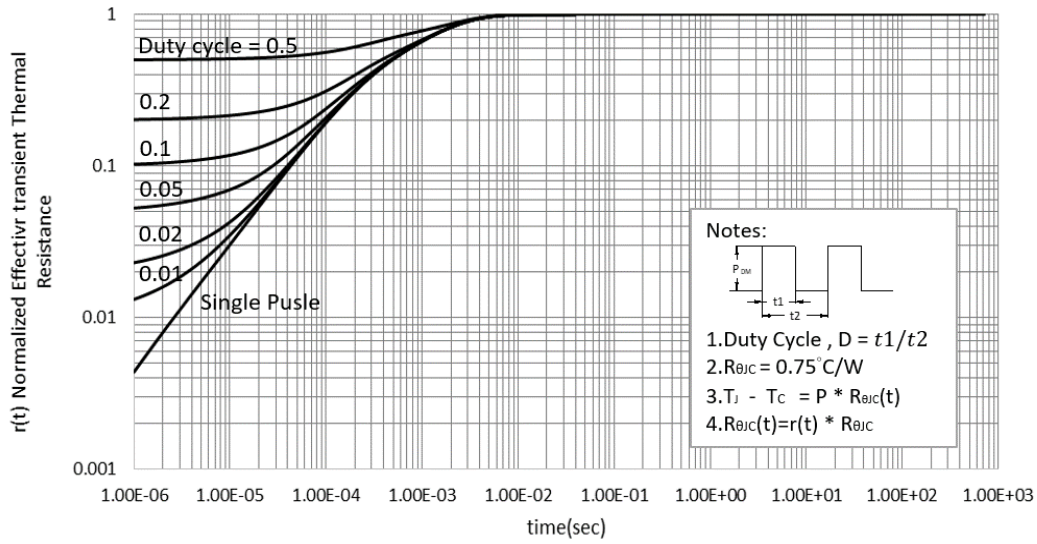


Fig 11. Effective Transient Thermal Impedance

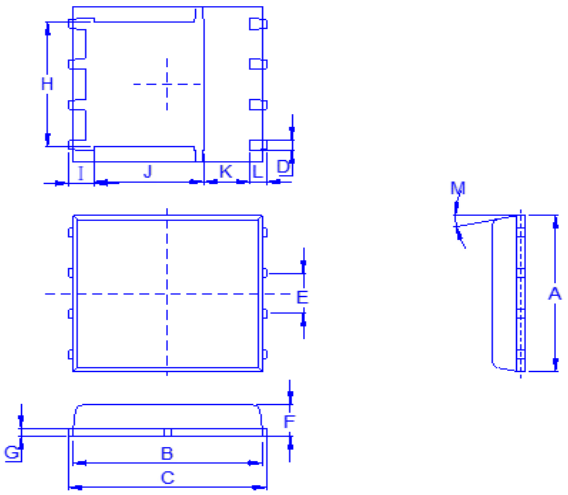
Ordering & Marking Information:

Device Name: EMB12N10H for EDFN 5x6

B12N10: Device Name

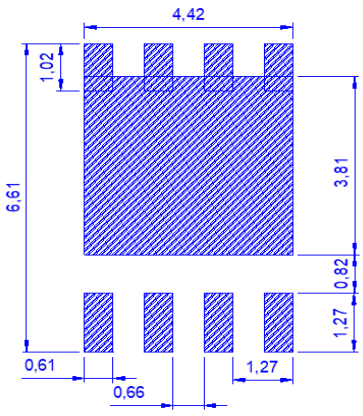
ABCDEFG: Date Code
A: Assembly House
B: Year(A:2008 B:2009 C:2010….)
C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)
DEFG: Serial No.

Outline Drawing

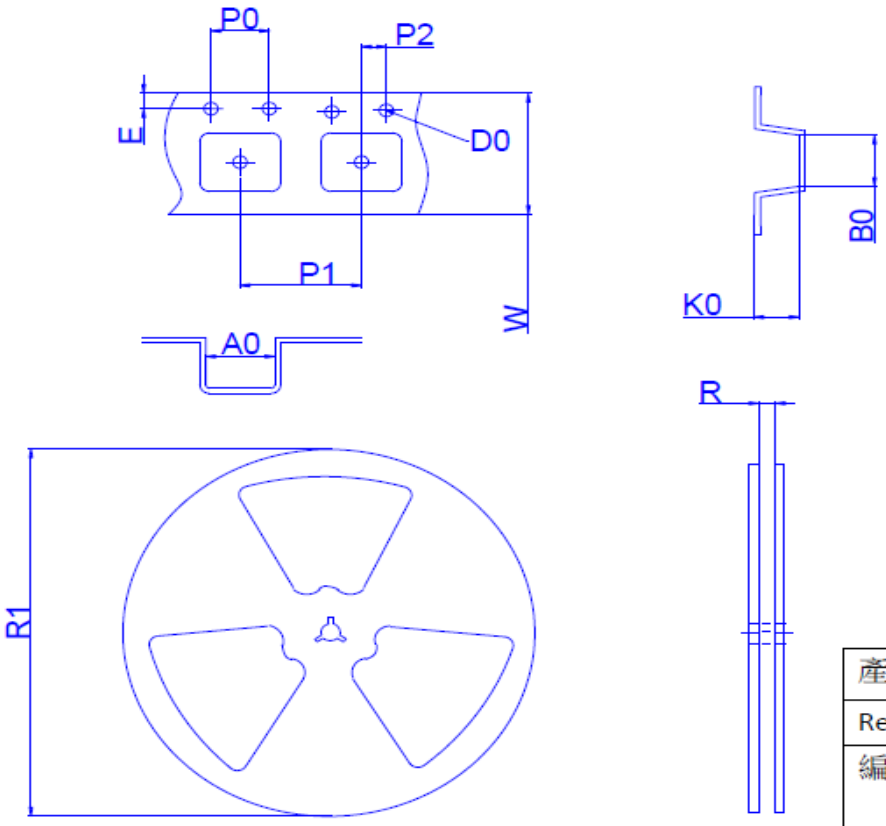


Dimension	A	B	C	D	E	F	G	H	I	J	K	L	M
Min.	4.8	5.55	5.9	0.3	1.17	0.85	0.15	3.61	0.38	3.18	1	0.38	0°
Typ.	4.9	5.7	6	0.4	1.27	0.95	0.2	3.87	0.4	3.44	1.195	0.4	
Max.	5.4	5.85	6.15	0.51	1.37	1.17	0.34	4.31	0.711	3.78	1.39	0.71	12°

Footprint



◆ **Tape&Reel Information:2500pcs/Reel**



產品別	EDFN 5*6
Reel 尺寸	13"
編帶方式	FEED DIRECTION

Dimension in mm

Dimension	Carrier tape									Reel	
	A0	B0	D0	E	K0	P0	P1	P2	W	R	R1
Typ.	6.4	5.3	1.5	1.8	1.6	4.0	8.0	2.0	12.0	17.0	330.0
±	0.2	0.2	0.1	0.1	0.6	0.1	0.1	0.1	0.3	2.0	2.0